

AgilLink™ 2.00mm Wire-to-Board Header G823 Series

CUSTOMIZABLE SHROUDED WIRE-TO-BOARD HEADER

AgilLink™ 2.00mm Wire-to-Board Header G823 Series is the most common solution for transferring power and signal. It can mate with both wire to board and board to board application. This series can carry a maximum current rating of 4A. Amphenol ICC offers a comprehensive range of these headers including, V/T DIP, V/T SMT, R/A DIP to meet various customer requirement. It comes in customizable pin length, including contact pin and solder tail, which makes it an ideal choice for several applications and specific designs.

- Flexible and easy to change pin lengths to meet various application requirements
- Cost-effective
- Suitable for both wire-to-board and board-to-board application
- Supports PIP process
- Easy pin insertion and high retention force onto PCB

FEATURES

- Customizable pin length, including contact pin and solder tail
- Various mounting options including vertical DIP, right angle DIP, vertical SMT and right angle SMT
- High temperature thermoplastic material
- Tape and reel packaging option
- RoHS compliance and halogen Free
- Stand-off design
- Meet USB2.0 and USB3.0 Signal
- Mates with Header WTB G862® and Header BTB G827



TARGET MARKETS



BENEFITS

- Suitable for different application and specific designs
- Ease in choosing board mating configurations
- Reflow compatible
- Supports PIP process
- Meets environmental, health and safety requirements
- Ease of cleaning the PCB
- Can meet 3G and 5G speed
- Mutually compatible for wire to board or board to board application

TECHNICAL INFORMATION

MATERIAL

- High temperature thermoplastic, UL 94 flammability rated
- Contacts: Copper alloy, selective gold plating or tin plated on contact area, selective gold plated or tin plated plating on solder tail and nickel plated under-plated overall

ELECTRICAL PERFORMANCE

- Current rating: 1.5A AC/DC
- Voltage rating: 250V DC
- Temperature: -25°C to +85°C
- Contact retention: Initial- 20mΩ max., after environmental test- 30mΩ max.
- Insulation resistance: 1000MΩ min.

MECHANICAL PERFORMANCE

- Contact retention: 1.00kgf min. before solder, 0.60kgf min. after solder
- Contact resistance: $\Delta R=10m\Omega$
- Maximum insertion force: 3.5N/ per pin max.
- Withdrawal force: 0.25N/ per pin min.

SPECIFICATION

- Amphenol Product Specification: PS-7522

ENVIRONMENTAL

- EIA 364-31 method III test condition A
- Temperature: 25°C to 65°C
- Humidity: 90% to 95% RH
- Period: 96 hours
- Salt Spray: 5% 48 hours at 35°C

PACKAGING

- Operating Procedure: #COP-15-1
- Packing Specification: PKS-0001

TARGET MARKETS/APPLICATIONS



Communications



Portable device



Mother board
Riser card
Signal transmission



POS
Smart meter
Control board



Medical